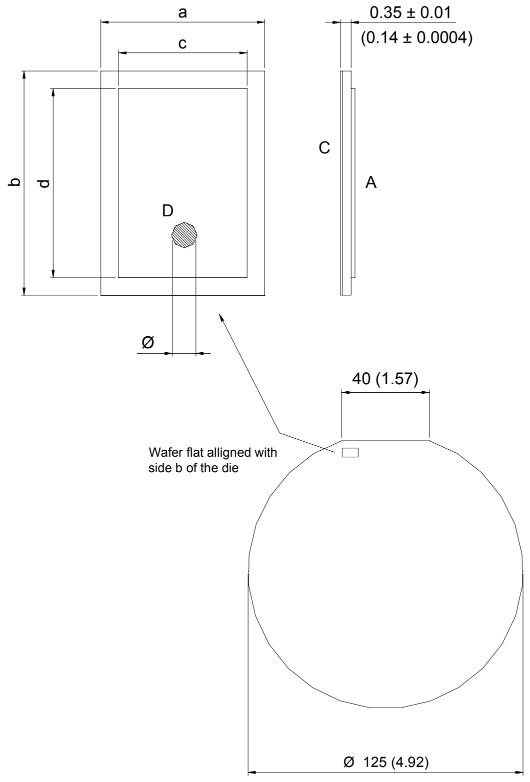
Preliminary Data Sheet I0405J 03/01

International
IOR Rectifier

SC021.....5. Series

SCHOTTKY DIE 21 x 45 mils



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
2. CONTROLLING DIMENSION: (INCH).
3. DIMENSIONS AND TOLERANCES:
   a = 0.53 + 0, - 0.05
   (0.021 + 0, - 0.002)
   b = 1.14 + 0, - 0.05
   (0.045 + 0, - 0.002)
   c = 0.38 + 0, - 0.003
   (0.015 + 0, - 0.0001)
   d = 0.99 + 0, - 0.003
   (0.399 + 0, - 0.0001)
   Ø = 0.7 ± 0.1
   (0.03 ± 0.004)
4. LETTER DESIGNATION:
   A = Anode (Top Metal)
   C = Cathode (Back Metal)
   D = Reject Ink Dot (only on non-conforming dies)
   (Sample Probe)
5. SAWING:
   Recommended Blade
   SEMITEC S1025 QS00 Blade

NOT TO SCALE

NOTE: **10 mils die thickness is available on specific request only.**
Contact factory for information.

Electrical Characteristics

Device #	T_J Max. (°C)	V_R (V)	Typ. I_R @ 25°C (µA)	Typ. I_R @ 125°C (mA)	Max. V_F @ I_F (V)	Package Style
SC021**R**015x5x	125	15	n.a. contact factory			
SC021**S**020x5x	150	20	n.a. contact factory			
SC021**S**030x5x	150	30	n.a. contact factory			
SC021**S**045x5x	150	45	n.a. contact factory			
SC021**S**060x5x	150	60	n.a. contact factory			
SC021**H**045x5x	175	45	n.a. contact factory			
SC021**H**100x5x	175	100	n.a. contact factory			
SC021**H**150x5x	175	150	n.a. contact factory			

Mechanical Data

Device #		Metal Thickness Front Metal			Metal Thickness Back Metal		
SC021xxxx**A**5x	Bondable	–	Al/Si 30 kÅ	–	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ
SC021xxxx**S**5x	Solderable	Ti 2 kÅ	Ni 1 kÅ	Ag 35 kÅ	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ

Recommended Storage Environment: Store in original container, in dessicated nitrogen, with no contamination.
Shelf life for parts stored in above condition is 2 years.
If the storage is done in normal atmosphere shelf life is reduced to six months.

Packaging

Device #	Description	Minimum Order Quantity Die in Sale Package
SC021xxxxx5**B**	Inked Probed Unsawn Wafer (Wafer in Box)	17500
SC021xxxxx5**R**	Probed Die in Tape & Reel	n.a.
SC021xxxxx5**P**	Probed Die in Waffle Pack	n.a.
SC021xxxxx5**F**	Inked Probed Sawn Wafer on Film	17500

Ordering Information Table

Device Code

SC	021	S	030	S	5	B
①	②	③	④	⑤	⑥	⑦

1 - Schottky Die

2 - Chip Dimension in Mils

3 - Process (see Electrical Characteristics Table)

H = 830 Process
R = OR'ing Process
S = Standard Process

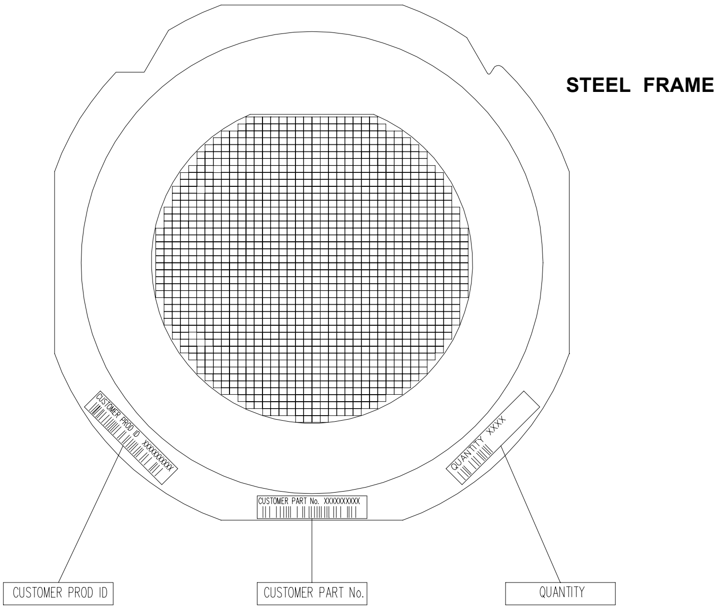
4 - Voltage code: Code = V_{RRM}

5 - Chip surface metallization (see Mechanical Data Table)

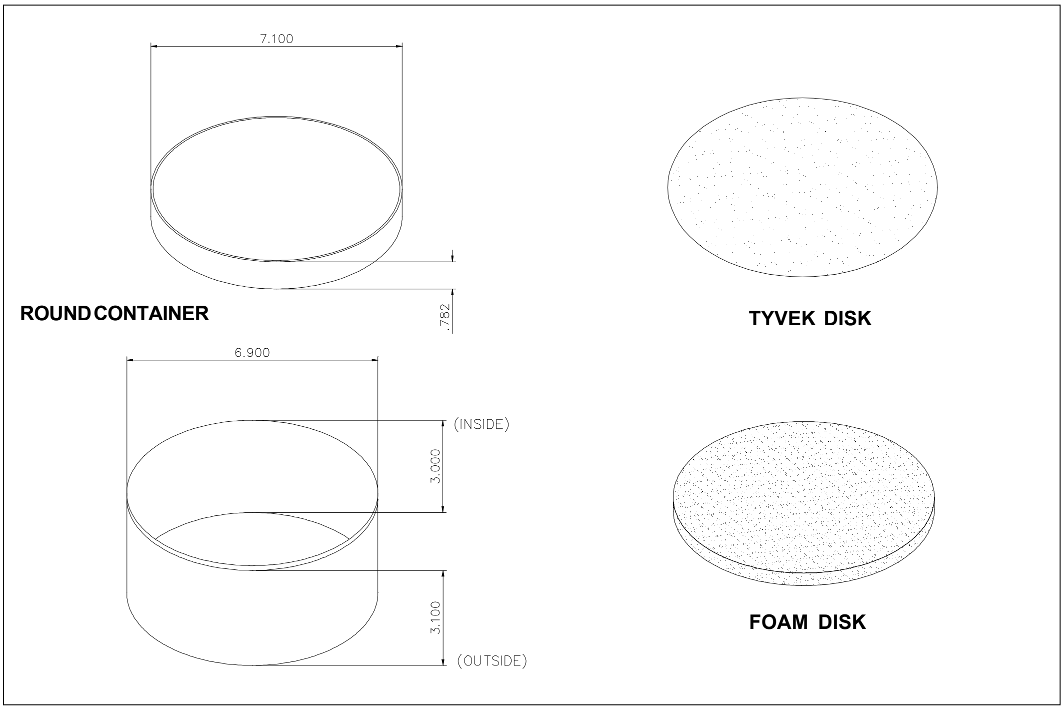
6 - Wafer Diameter in inches

7 - Packaging (see Packaging Table)

Wafer on Film



Wafer in Box



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